



6
BT
03-06-02

Docket No. 214133US2PCT/In

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

IN RE APPLICATION OF: Katsuya MURAKAMI, et al.

SERIAL NO: 09/926,317

GAU: 2834

FILED: October 12, 2001

EXAMINER:

FOR: PRODUCT WITH CONDUCTING PARTS MADE OF HIGHLY CONDUCTIVE RESIN, AND METHOD OF MANUFACTURE THEREOF

INFORMATION DISCLOSURE/RELATED CASE STATEMENT UNDER 37 CFR 1.97

ASSISTANT COMMISSIONER FOR PATENTS
WASHINGTON, D.C. 20231

SIR:

Applicant(s) wish to disclose the following information.

REFERENCES

- ☒ The applicant(s) wish to make of record the references listed on the attached form PTO-1449. Copies of the listed references are attached, where required, as are either statements of relevancy or any readily available English translations of pertinent portions of any non-English language references.
- ☐ A check is attached in the amount required under 37 CFR §1.17(p).

RELATED CASES

- ☐ Attached is a list of applicant's pending application(s) or issued patent(s) which may be related to the present application. A copy of the patent(s), together with a copy of the claims and drawings of the pending application(s) is attached along with PTO 1449.
- ☐ A check is attached in the amount required under 37 CFR §1.17(p).

CERTIFICATION

- ☐ Each item of information contained in this information disclosure statement was first cited in any communication from a foreign patent office in a counterpart foreign application not more than three months prior to the filing of this statement.
- ☐ No item of information contained in this information disclosure statement was cited in a communication from a foreign patent office in a counterpart foreign application or, to the knowledge of the undersigned, having made reasonable inquiry, was known to any individual designated in 37 CFR §1.56(c) more than three months prior to the filing of this statement.

DEPOSIT ACCOUNT

- ☒ Please charge any additional fees for the papers being filed herewith and for which no check is enclosed herewith, or credit any overpayment to deposit account number 15-0030. A duplicate copy of this sheet is enclosed.

Respectfully submitted,

OBLON, SPIVAK, McCLELLAND,
MAIER & NEUSTADT, P.C.

Joseph A. Scafetta Jr.

Marvin J. Spivak
Registration No. 24,913

Joseph A. Scafetta, Jr.
Registration No. 26,803

RECEIVED
FEB - 4 2002
TECHNOLOGY CENTER 2800



22850

Tel. (703) 413-3000
Fax. (703) 413-2220
(OSMMN 10/98)

DOCKET NO: 214133US2PCT

Sheet 1 of 1

SERIAL NO: 09/926,317

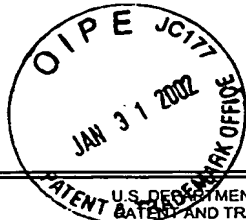
Group Art Unit: 2834



STATEMENT OF RELEVANCY

References AG (JP 6-105487) and AO (JP 9-250420) on Form 1449 are discussed in the specification

RECEIVED
FEB -4 2002
TECHNOLOGY CENTER 2800



Form PTO 1449 (Modified)		U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE		ATTY DOCKET NO. 214133US2PCT		SERIAL NO. 09/926,317	
LIST OF REFERENCES CITED BY APPLICANT				APPLICANT Katsuya MURAKAMI, et al.			
				FILING DATE October 12, 2001		GROUP 2834	
U.S. PATENT DOCUMENTS							
EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUB CLASS	FILING DATE IF APPROPRIATE
	AA						
	AB						
	AC						
	AD						
	AE						
	AF						
FOREIGN PATENT DOCUMENTS							
		DOCUMENT NUMBER	DATE	COUNTRY	TRANSLATION YES NO		
	AG	6-105487	04/15/94	JAPAN			X
	AH	03-155353	07/03/91	JAPAN (with English Abstract)			X
	AI	64-069237	03/15/89	JAPAN (with English Abstract)			X
	AJ	62-274559	11/28/87	JAPAN (with English Abstract)			X
	AK	63-308874	12/16/88	JAPAN (with English Abstract)			X
	AL	06-333580	12/02/94	JAPAN (submitting English Abstract only)			
	AM	10-079260	03/24/98	JAPAN (with English Abstract)			X
	AN	08-334075	12/17/96	JAPAN (with English Abstract)			X
	AO	9-250420	09/22/97	JAPAN			X
	AP	11-264361	09/28/99	JAPAN (with English Abstract)			X
	AQ						
	AR						
	AS						
	AT						
	AU						
	AV						
OTHER REFERENCES (Including Author, Title, Date, Pertinent Pages, etc.)							
	AW	H. NOGUCHI, et al., Proceedings of the 75 th JSME Spring Annual Meeting of the Japan Society of Mechanical Engineers, no. 2, pages 696-697, "CONDUCTIVE COMPOSITE MATERIAL FOR INJECTION WRITING USING METAL POWDERS", 1998 (with Concise English Explanation)					
	AX	T. NAKAGAWA, The Journal of the Japan Society of Polymer Processing, vol. 9, no. 4, pages 247-251, "ON THE MOLDED INTERCONNECT DEVICE", 1997 (with Concise English Explanation)					
	AY	H. NOGUCHI, et al., The Monthly Journal of Institute of Industrial Science, University Tokyo, vol. 48, no. 4, pages 258-261, "DEVELOPMENT OF HIGHLY CONDUCTIVE POLYMER COMPOSITE FOR 3D WIRING CIRCUIT BY INJECTION MOLDING", 1996 (with Concise English Explanation)					
	AZ	H. NOGUCHI, et al., The Proceedings of the 11 th Meeting of the Japan Institute of Printed Circuits, pages 145-146, "SOLDER-DISSIPATING TYPE OF CONDUCTIVE PLASTICS -THE FOURTH REPORT: DISSIPATION OF LEAD-FREE SOLDER", March 1997 (with Concise English Explanation)					
Examiner					Date Considered		
*Examiner: Initial if reference is considered; whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.							